Version With Markings To Show Changes Made

In the Claims:

Please amend the claims as follows:

37. (Amended) The method of claim [32] 36, wherein said step of securing said third material comprises securing said third [piece of tape] material on said die.

38. (Amended) The method of claim [32] 36, wherein said step of securing said third material comprises securing said third [piece of tape] material on said circuit board.

39. (Amended) The method of claim [32] 36, wherein said step of securing said third material comprises applying a thin layer of material on said die, said thin layer of material contacting said first and second adhesive materials to form a diversion dam.

40. (Amended) The method of claim [32] 36, wherein said step of securing said third material comprises applying a thin layer of material on said circuit board, said thin layer of material contacting said first and second adhesive materials to form a diversion dam.

In the Abstract of the Disclosure:

Please amend the abstract as follows:

An [efficient] adhesive system and a method of adhesion for a ball grid array semi-conductor device package [which allows for better] facilitate the encapsulation

[are disclosed] of a die attached to a circuit board. A material is added between a die and a circuit board tape, [which] and is oriented perpendicular to a conventional two-piece tape system used to [attached] attach the die to the circuit board. The material, which is located across from a gate through which [injects] an encapsulation [material] compound is injected to form a package, [and] acts as a diversion dam [causing a compound injected during encapsulation]. The material thereby enables the injected encapsulation compound to fill a wirebond slot last and avoid [a compound] an overflow which might otherwise damage the ball [gird] grid array.